

P-Channel 100 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | |
|---------------------|------------------------------------|--------------------|-----------------------|--|--|
| V _{DS} (V) | $R_{DS(on)}(\Omega)$ | I _D (A) | Q _g (Typ.) | | |
| - 100 | 0.180 at $V_{GS} = -10 \text{ V}$ | - 7.5 | 11 | | |
| - 100 | 0.200 at V _{GS} = - 4.5 V | - 6 | 11 | | |

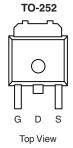
FEATURES

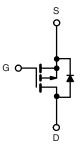
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

- · Power Switch
- DC/DC Converters





P-Channel MOSFET

| Parameter | Symbol | Limit | Unit | |
|---|-------------------------------------|-----------------------------------|-------------------|-----|
| Drain-Source Voltage | V _{DS} | - 100 | V | |
| Gate-Source Voltage | | V _{GS} | ± 20 | 7 v |
| Continuous Drain Current (T _{.I} = 150 °C) | T _C = 25 °C | I _D | - 7.5 | |
| Continuous Diain Current (1) = 150 C) | T _C = 70 °C | D 'D | - 7 | |
| Pulsed Drain Current | I _{DM} | - 80 | Α Α | |
| Avalanche Current | | I _{AS} | - 18 | |
| Single Avalanche Energy ^a | L = 0.1 mH | E _{AS} | 16.2 | mJ |
| Mariana Barra Biratina | T _C = 25 °C | Р | 32.1 ^b | 10/ |
| Maximum Power Dissipation ^a | T _A = 25 °C ^c | $ P_{D}$ $-$ | 2.5 | - w |
| Operating Junction and Storage Temperature Rai | nge | T _J , T _{sta} | - 55 to 150 | °C |

| THERMAL RESISTANCE RATINGS | | | | | |
|--|-------------------|-------|------|--|--|
| Parameter | Symbol | Limit | Unit | | |
| Junction-to-Ambient (PCB Mount) ^c | R _{thJA} | 50 | °C/W | | |
| Junction-to-Case (Drain) | R _{thJC} | 3.9 | C/VV | | |

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

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| SPECIFICATIONS T _J = 25 °C, unless otherwise noted | | | | | | | |
|---|----------------------|--|-------|-------|-------|------|--|
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$ | - 100 | | | V | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | - 1 | | - 2.5 | V | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 250 | nA | |
| | | V _{DS} = - 100 V, V _{GS} = 0 V | | | - 1 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = - 100 V, V _{GS} = 0 V, T _J = 125 °C | | | - 50 | μΑ | |
| | | V _{DS} = - 100 V, V _{GS} = 0 V, T _J = 150 °C | | | - 250 | 1 | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$ | - 15 | | | Α | |
| D : 0 | D | V _{GS} = - 10 V, I _D = - 3.6 A | | | 0.180 | Ω | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = - 4.5 V, I _D = - 3.4 A | | | 0.200 | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = - 15 V, I _D = - 3.6 A | | 12 | | S | |
| Dynamic ^b | • | | | • | • | | |
| Input Capacitance | C _{iss} | | | 1055 | | pF | |
| Output Capacitance | C _{oss} | $V_{GS} = 0 \text{ V}, V_{DS} = -50 \text{ V}, f = 1 \text{ MHz}$ | | 65 | | | |
| Reverse Transfer Capacitance | C _{rss} |] | | 41 | | | |
| Total Gate Charge ^c | Qq | V _{DS} = - 50 V, V _{GS} = - 10 V, I _D = - 3.6 A | | | 15 | | |
| Total Gate Charge | ŭ | | | | 11 | nC | |
| Gate-Source Charge ^c | Q_{gs} | $V_{DS} = -50 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -3.6 \text{ A}$ | | | 3.5 | liC | |
| Gate-Drain Charge ^c | Q_{gd} | | | | 4.8 | | |
| Gate Resistance | R_g | f = 1 MHz | 1.2 | 5.7 | 11.5 | Ω | |
| Turn-On Delay Time ^c | t _{d(on)} | | | 7 | 14 | | |
| Rise Time ^c | t _r | $V_{DD} = -50 \text{ V}, R_L = 17.2 \Omega$ | | 12 | 18 | ns | |
| Turn-Off Delay Time ^c | t _{d(off)} | $I_D \cong$ - 2.9 A, V_{GEN} = - 10 V, R_g = 1 Ω | | 33 | 50 | 115 | |
| Fall Time ^c | t _f | | | 9 | 18 | | |
| Drain-Source Body Diode Ratings a | nd Characteri | stics T _C = 25 °C ^b | | | | | |
| Continuous Current | I _S | | | | - 8.8 | ۸ | |
| Pulsed Current | I _{SM} | | | | - 15 | A | |
| Forward Voltage ^a | V_{SD} | I _F = - 2.9 A, V _{GS} = 0 V | | - 0.8 | - 1.5 | V | |
| Reverse Recovery Time | t _{rr} | | | 50 | 75 | ns | |
| Peak Reverse Recovery Current | I _{RM(REC)} | I _F = - 2.9 A, dl/dt = 100 A/μs | | - 4 | - 6 | Α | |
| Reverse Recovery Charge | Q _{rr} |] | | 98 | 147 | nC | |

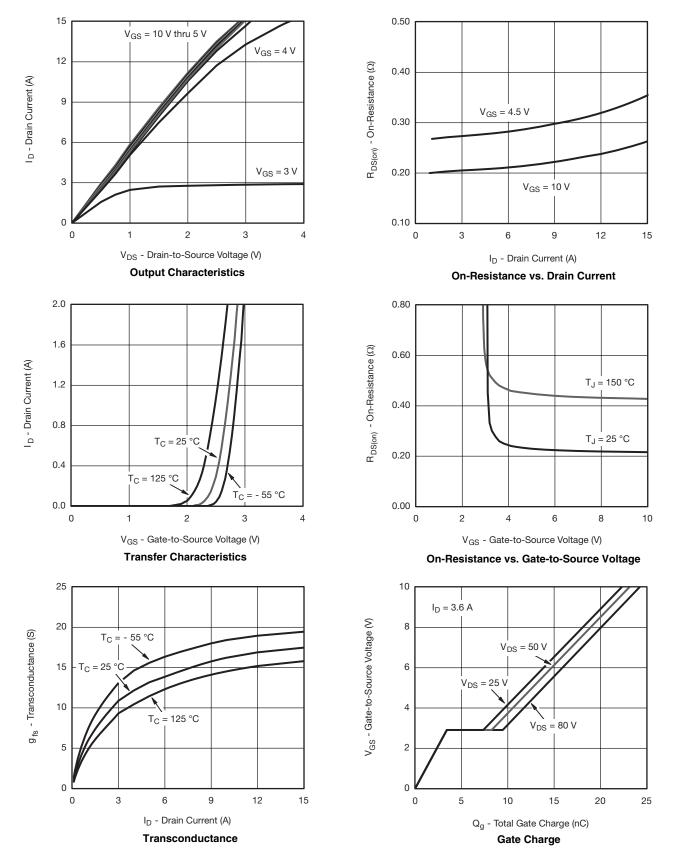
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

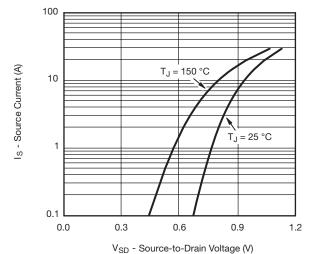


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

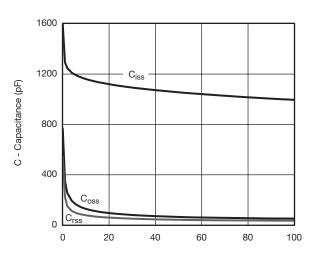




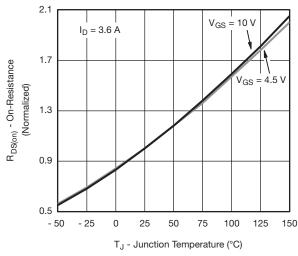
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



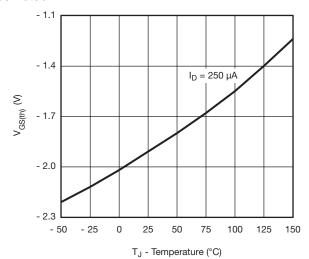
Source-Drain Diode Forward Voltage



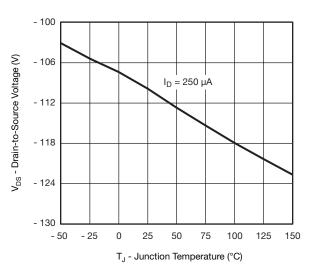
 V_{DS} - Drain-to-Source Voltage (V) $\label{eq:capacitance}$



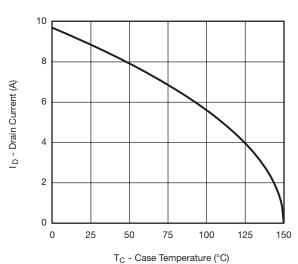
On-Resistance vs. Junction Temperature



Threshold Voltage



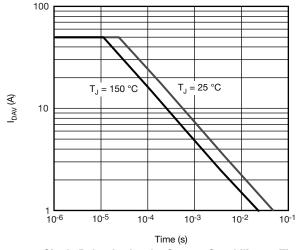
Drain Source Breakdown vs. Junction Temperature

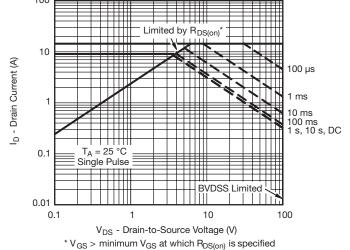


Current Derating



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

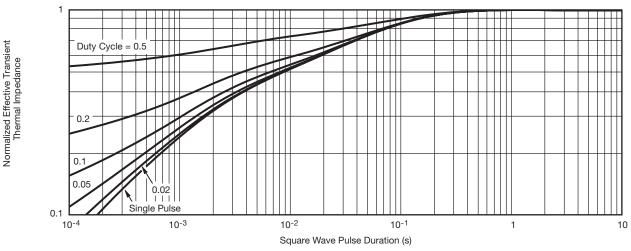




Single Pulse Avalanche Current Capability vs. Time



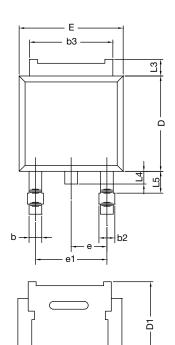


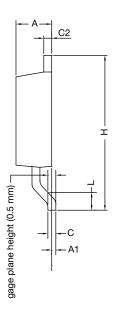


Normalized Thermal Transient Impedance, Junction-to-Case



TO-252AA Case Outline





| | MILLIN | /IETERS | INCHES | | |
|-----------|------------|-----------|-----------|--------|--|
| DIM. | MIN. | MAX. | MIN. | MAX. | |
| Α | 2.18 | 2.38 | 0.086 | 0.094 | |
| A1 | - | 0.127 | - | 0.005 | |
| b | 0.64 | 0.88 | 0.025 | 0.035 | |
| b2 | 0.76 | 1.14 | 0.030 | 0.045 | |
| b3 | 4.95 | 5.46 | 0.195 | 0.215 | |
| С | 0.46 | 0.61 | 0.018 | 0.024 | |
| C2 | 0.46 | 0.89 | 0.018 | 0.035 | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | |
| D1 | 4.10 | - | 0.161 | - | |
| Е | 6.35 | 6.73 | 0.250 | 0.265 | |
| E1 | 4.32 | - | 0.170 | - | |
| Н | 9.40 | 10.41 | 0.370 | 0.410 | |
| е | 2.28 BSC | | 0.090 BSC | | |
| e1 | 4.56 | BSC 0. | | 30 BSC | |
| L | 1.40 | 1.78 | 0.055 | 0.070 | |
| L3 | 0.89 | 1.27 | 0.035 | 0.050 | |
| L4 | - | 1.02 | - | 0.040 | |
| L5 | 1.01 | 1.52 | 0.040 | 0.060 | |
| FCN: T16- | 0236-Rev P | 16-May-16 | | | |

ECN: T16-0236-Rev. P, 16-May-16 DWG: 5347

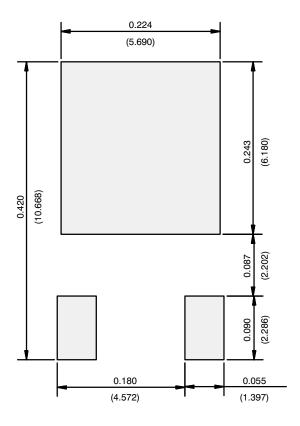
Notes

• Dimension L3 is for reference only.

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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